# 2SD2213

## Silicon NPN Epitaxial, Darlington

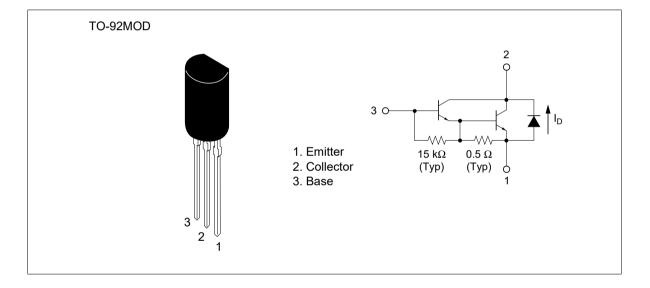
# **HITACHI**

ADE-208-1165 (Z) 1st. Edition Mar. 2001

#### **Application**

Low frequency power amplifier

#### Outline





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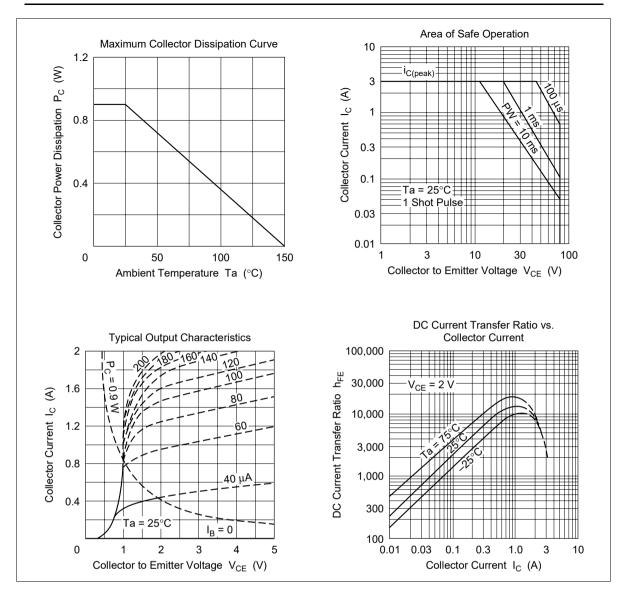
## **Absolute Maximum Ratings** (Ta = 25°C)

Item	Symbol	Ratings	Unit
Collector to base voltage	$V_{\text{CBO}}$	150	V
Collector to emitter voltage	V <sub>CEO</sub>	80	V
Emitter to base voltage	$V_{EBO}$	8	V
Collector current	I <sub>c</sub>	1.5	А
Collector peak current	ic <sub>(peak)</sub>	3	А
Collector power dissipation	P <sub>c</sub>	0.9	W
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C
E to C diode forward current	I <sub>D</sub>	1.5	А

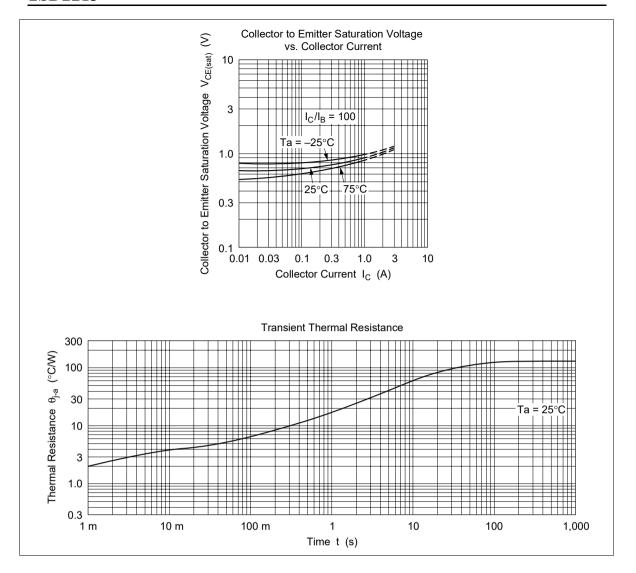
#### **Electrical Characteristics** (Ta = 25°C)

Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	150	_	_	V	$I_{c} = 1 \text{ mA}, I_{E} = 0$
Collector to emitter breakdown voltage	$V_{\text{(BR)CEO}}$	80	_	_	V	$I_{\rm C}$ = 10 mA, $R_{\rm BE}$ = $\infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	8	_	_	V	$I_{\rm E}$ = 50 mA, $I_{\rm C}$ = 0
Collector cutoff current	I <sub>CBO</sub>	_	_	5.0	μΑ	V <sub>CB</sub> = 120 V, I <sub>E</sub> = 0
	I <sub>CEO</sub>	_	_	5.0	μΑ	V <sub>CE</sub> = 65 V, I <sub>E</sub> = ∞
DC current transfer ratio	h <sub>FE</sub>	2000	_	_		$V_{CE} = 2 \text{ V}, I_{C} = 0.15 \text{ A}^{*1}$
	h <sub>FE</sub>	5000	_	30000		$V_{CE} = 2 \text{ V}, I_{C} = 1 \text{ A}^{*1}$
_	$h_{\text{FE}}$	1000	_	_		$V_{CE} = 2 \text{ V}, I_{C} = 1.5 \text{ A}^{*1}$
Collector to emitter saturation voltage	$V_{\text{CE}(\text{sat})}$	_	_	1.5	V	$I_{C} = 1 A^{*1}, I_{B} = 1 mA$
Base to emitter saturation voltage	$V_{BE(sat)}$	_	_	2.0	V	I <sub>C</sub> = 1 A* <sup>1</sup> , I <sub>B</sub> = 1 mA
E to C diode forward voltage	V <sub>D</sub>	_	_	3.0	V	I <sub>D</sub> = 1.5 A*1

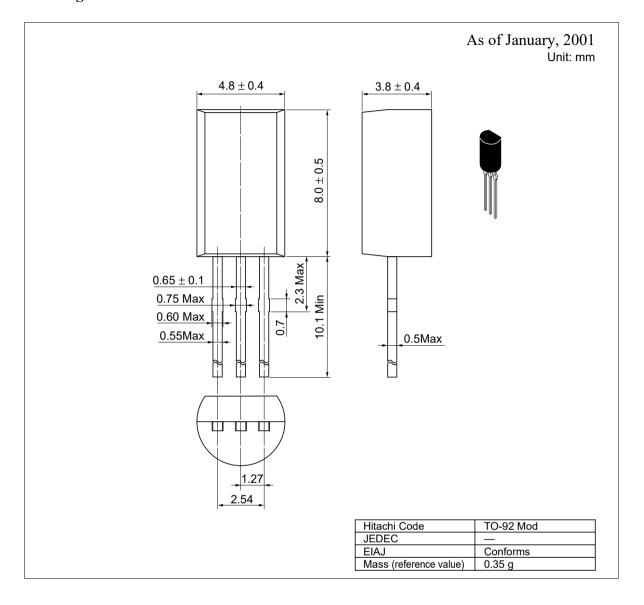
Note: 1. Pulse test



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#### **Package Dimensions**



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